

MicroStar BGA Discontinued and Redesigned



Low Power Audio & Actuators

ABSTRACT

This document should be used in conjunction with the device data sheet and describes the updated package designator for the indicated devices.

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Trademarks

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1 Package Redesign Details

Explanation

The devices in the MicroStar BGA™ packaging were redesigned using a laminate nfBGA package. The nfBGA package offers data sheet-equivalent electrical performance. It is also footprint equivalent to the MicroStar BGA. For more details, please refer to this [nfBGA Package Application Report](#).

When referencing the device data sheet, use the new package designator in place of the discontinued package designator throughout the document.

The orderable addendum at the end of the device data sheet will reflect the new package designator.

See the following page or the end of the device data sheet for the updated nfBGA package drawing.

Table 1-1. Package Designator

Old Package Designator	New Package Designator
ZQV	NMB

Reason for Discontinuance

Due to an equipment End-Of-Life notice from our substrate supplier, we are phasing out certain MicroStar BGA and MicroStar Junior™ BGA packaging devices and offering a Last Time Buy.

These devices have now been converted to an nfBGA package.

Devices Affected

The following table describes the devices affected, the old and new package designators, and references to the device data sheet.

Table 1-2. Devices and Nomenclature

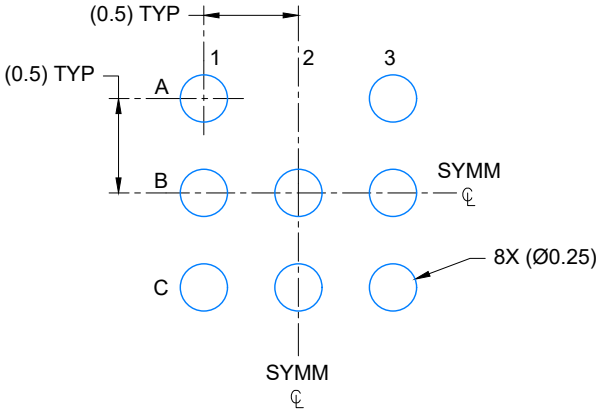
Device	Discontinued MicroStar BGA Device	Redesigned Laminate nfBGA Device	Device Data Sheet
DRV8601	DRV8601 ZQVR	DRV8601 NMBR	SLOS629D
TPA6205A1	TPA6205A1 ZQVR	TPA6205A1 NMBR	SLOS490C
TPA6203A1	TPA6203A1 ZQVR	TPA6203A1 NMBR	SLOS364F

EXAMPLE BOARD LAYOUT

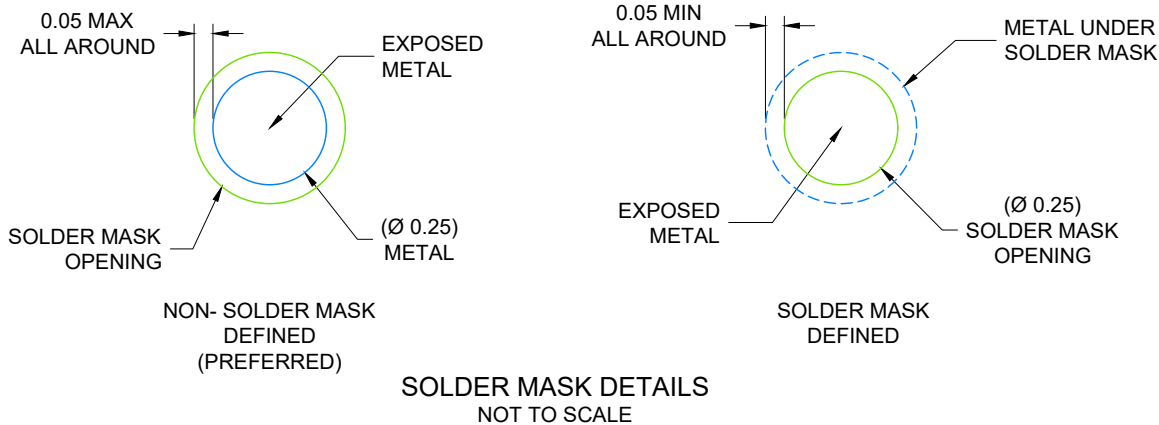
NFBGA - 1 mm max height

NMB0008A

PLASTIC BALL GRID ARRAY



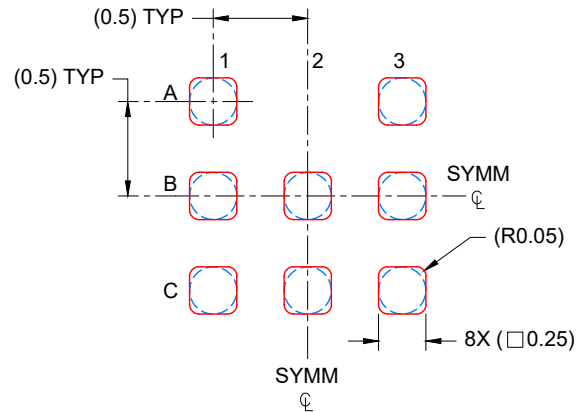
LAND PATTERN EXAMPLE
SCALE: 25X



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NOTES: (continued)

- 3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. Refer to Texas Instruments Literature number SNVA009 (www.ti.com/lit/snva009).



SOLDER PASTE EXAMPLE
BASED ON 0.100 mm THICK STENCIL
SCALE: 25X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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